

SPI 2021

25th IEEE Workshop On Signal And Power Integrity

May 10-12 2021, Virtual Online Conference

www.spi-conference.org ✉ spi@uni-siegen.de

Workshop Chair

Elmar Griese
University of Siegen (GER)

Thomas Kühler
University of Siegen (GER)

Program Co-Chair

Frank Gronwald
University of Siegen (GER)

Christian Schuster
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Madhavan Swaminathan
Georgia Institute of Technology, Atlanta (USA)

Important Dates

Full Paper Submission: Jan 31st, 2021

Notification of Acceptance: Feb 28th, 2021

Call for Papers

25th IEEE Workshop On Signal And Power Integrity May 10-12, 2021

Over the past two decades, the IEEE Workshop on Signal and Power Integrity (SPI) has evolved into a forum of exchange on the latest research and developments on design, characterization, modeling, simulation and testing for Signal and Power Integrity at chip, package, board and system level. The workshop brings together developers and researchers from industry and academia in order to encourage cooperation.

The Committee is looking forward to the 25th Edition which will be held as virtual online conference. The SPI 2021 technical program will consist of on-topic video sessions with consecutive panel discussions. A number of prominent experts will be giving tutorials on areas of emerging interest. The Conference Proceedings will be published with an ISBN code and will appear in IEEE Xplore.

Topics

- Modeling and simulation for SI/PI
- Coupled signal and power Integrity analysis
- Noise reduction and equalization techniques
- High-speed link design and modeling
- Power distribution networks
- RF/microwave/mm-wave systems and packaging solutions
- Antennas-in-package and antennas-on-chip
- 3D IC and packages (TSV/SiP/SoC)
- Nano-interconnects and nano-structures
- Electromagnetic theory and modeling
- Transmission line theory and modeling
- Macromodeling, reduced order models
- Electromagnetic compatibility
- Design methodology/flow measurements
- Jitter and noise modeling
- Stochastic/sensitivity analysis
- Electro-thermal modeling
- Chip-package co-design
- Novel CAD concepts
- Optical interconnects
- AI in electronics design



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